

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

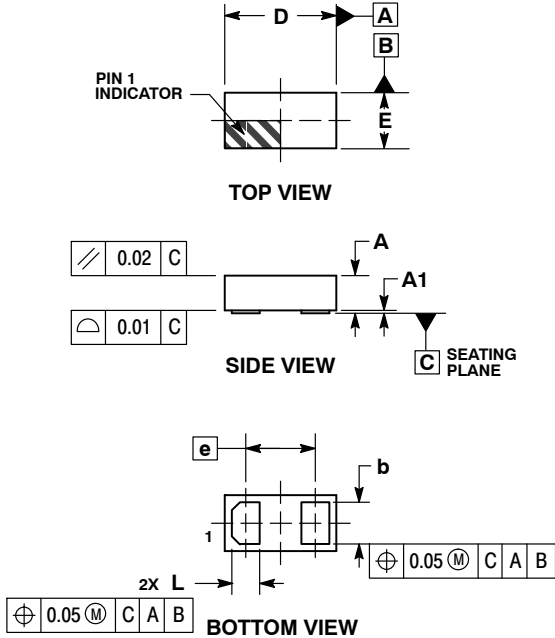
ON Semiconductor®



SCALE 8:1

**X4DFN2, 0.60x0.30, 0.36P**  
CASE 152AX  
ISSUE G

DATE 12 APR 2019

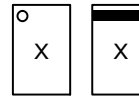


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.175	0.200	0.225
A1	0.018 REF		
b	0.205	0.215	0.225
D	0.575	0.600	0.625
E	0.275	0.300	0.325
e	0.36 BSC		
L	0.145	0.155	0.165

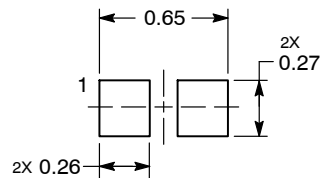
**GENERIC MARKING DIAGRAM\***



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

**RECOMMENDED SOLDER FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>X4DFN2, 0.60x0.30, 0.36P</b>	<b>PAGE 1 OF 1</b>

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